International
IOR Rectifier

PD- 93884C

SMPS MOSFET

IRF7466

HEXFET® Power MOSFET

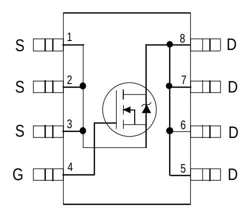
Applications

- High Frequency Isolated DC-DC Converters with Synchronous Rectification for Telecom and Industrial Use
- High Frequency Buck Converters for Computer Processor Power

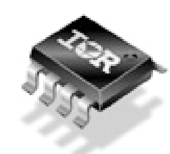
Benefits

- Ultra-Low Gate Impedance
- Very Low $R_{DS(on)}$
- Fully Characterized Avalanche Voltage and Current

V_{DSS}	$R_{DS(on)}$ max(mΩ)	I_D
30V	**12.5@V_{GS} = 10V**	**11A**



Top View


SO-8

Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ 10V	11	A
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ 10V	9.0	
I_{DM}	Pulsed Drain Current①	90	
P_D @T_A = 25°C	Maximum Power Dissipation③	2.5	W
P_D @T_A = 70°C	Maximum Power Dissipation③	1.6	W
	Linear Derating Factor	0.02	mW/°C
T_J , T_{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JL}$	Junction-to-Drain Lead	——	20	°C/W
$R_{\theta JA}$	Junction-to-Ambient ④	——	50	

Notes ① through ④ are on page 8

3/25/01

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30	–––	–––	V	V_{GS} = 0V, I_D = 250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	–––	0.028	–––	V/°C	Reference to 25°C, I_D = 1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	–––	9.8	12.5	mΩ	V_{GS} = 10V, I_D = 11A ③
		–––	13	17		V_{GS} = 4.5V, I_D = 8.8A ③
$V_{GS(th)}$	Gate Threshold Voltage	1.0	–––	3.0	V	V_{DS} = V_{GS}, I_D = 250µA
I_{DSS}	Drain-to-Source Leakage Current	–––	–––	20	µA	V_{DS} = 24V, V_{GS} = 0V
		–––	–––	100		V_{DS} = 24V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	–––	–––	200	nA	V_{GS} = 16V
	Gate-to-Source Reverse Leakage	–––	–––	-200		V_{GS} = -16V

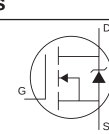
Dynamic @ T_J = 25°C (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	22	–––	–––	S	V_{DS} = 15V, I_D = 8.8A
Q_g	Total Gate Charge	–––	16	23	nC	I_D = 8.8A
Q_{gs}	Gate-to-Source Charge	–––	7.4	11		V_{DS} = 15V
Q_{gd}	Gate-to-Drain ("Miller") Charge	–––	5.3	8.0		V_{GS} = 4.5V ③
Q_{oss}	Output Gate Charge	–––	19	29		V_{GS} = 0V, V_{DS} = 15V
$t_{d(on)}$	Turn-On Delay Time	–––	10	–––	ns	V_{DD} = 15V
t_r	Rise Time	–––	2.8	–––		I_D = 8.8A
$t_{d(off)}$	Turn-Off Delay Time	–––	13	–––		R_G = 1.8Ω
t_f	Fall Time	–––	3.6	–––		V_{GS} = 4.5V ③
C_{iss}	Input Capacitance	–––	2100	–––	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	–––	710	–––		V_{DS} = 15V
C_{rss}	Reverse Transfer Capacitance	–––	52	–––		ƒ = 1.0MHz

Avalanche Characteristics

Symbol	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	–––	230	mJ
I_{AR}	Avalanche Current①	–––	8.8	A

Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	–––	–––	2.3	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	–––	–––	90		
V_{SD}	Diode Forward Voltage	–––	0.8	1.3	V	T_J = 25°C, I_S = 8.8A, V_{GS} = 0V ③
		–––	0.66	–––		T_J = 125°C, I_S = 8.8A, V_{GS} = 0V ③
t_{rr}	Reverse Recovery Time	–––	42	63	ns	T_J = 25°C, I_F = 8.8A, V_R=15V
Q_{rr}	Reverse Recovery Charge	–––	59	89	nC	di/dt = 100A/µs ③
t_{rr}	Reverse Recovery Time	–––	42	63	ns	T_J = 125°C, I_F = 8.8A, V_R=15V
Q_{rr}	Reverse Recovery Charge	–––	61	92	nC	di/dt = 100A/µs ③

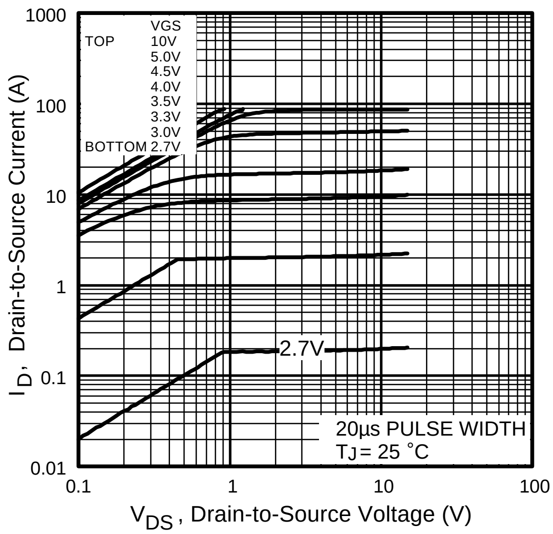


Fig 1. Typical Output Characteristics

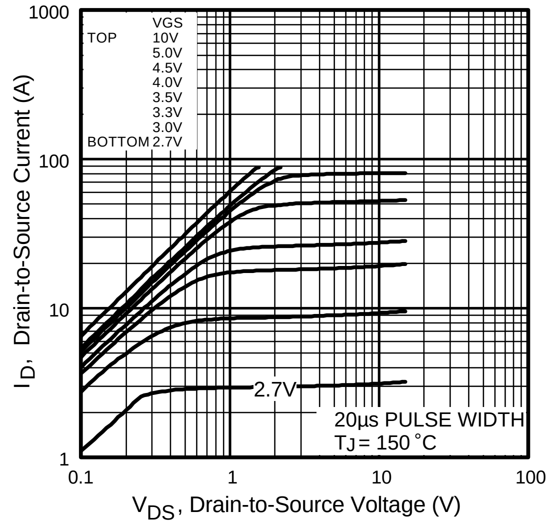


Fig 2. Typical Output Characteristics

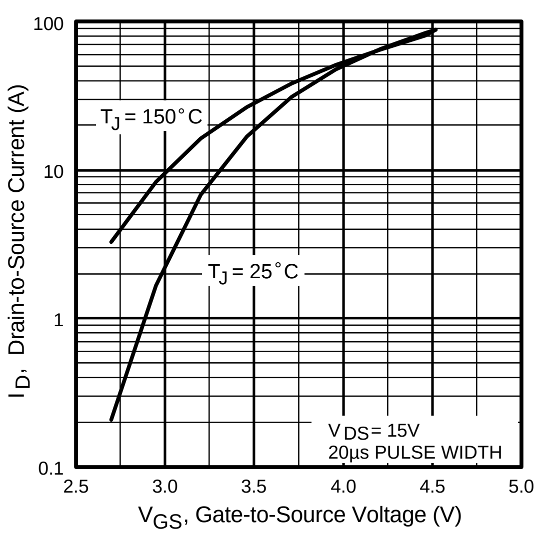


Fig 3. Typical Transfer Characteristics

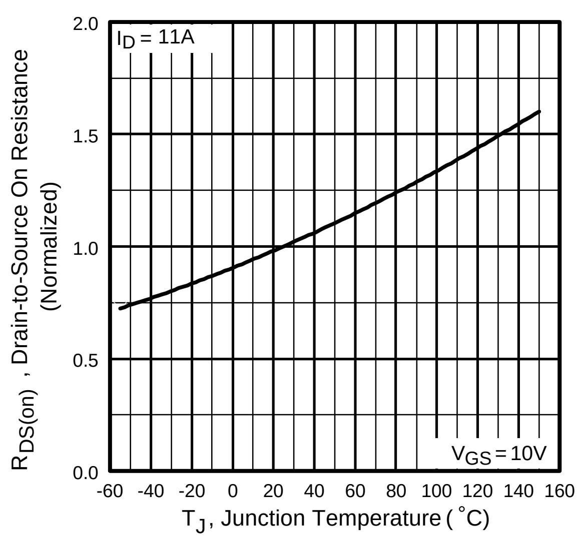


Fig 4. Normalized On-Resistance Vs. Temperature

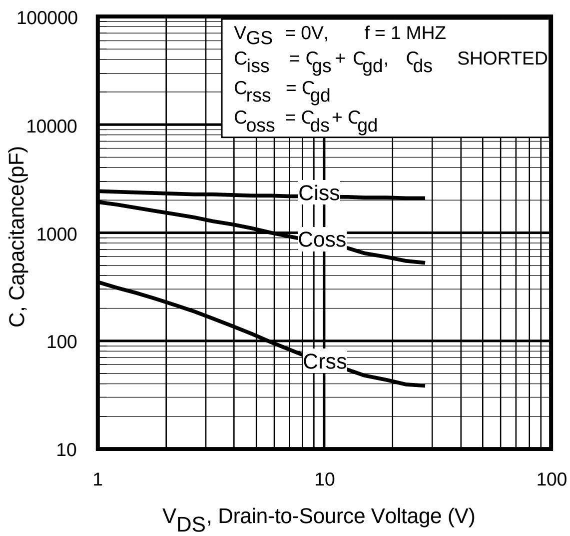


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

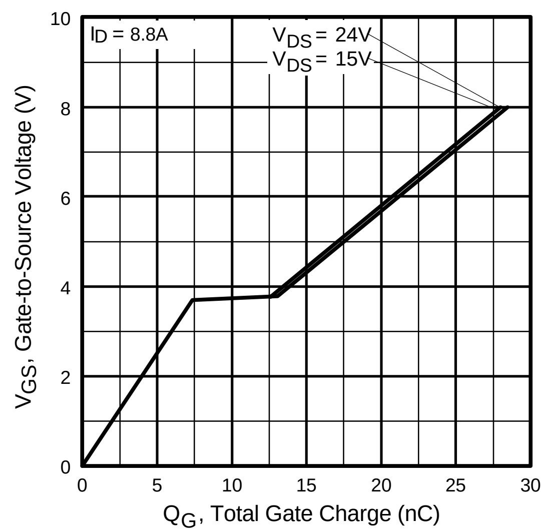


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

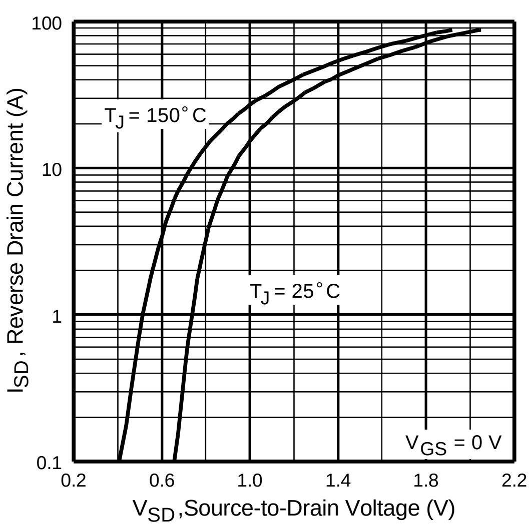


Fig 7. Typical Source-Drain Diode Forward Voltage

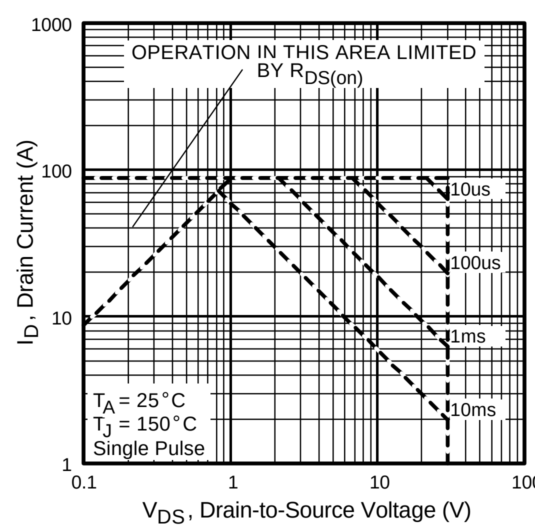
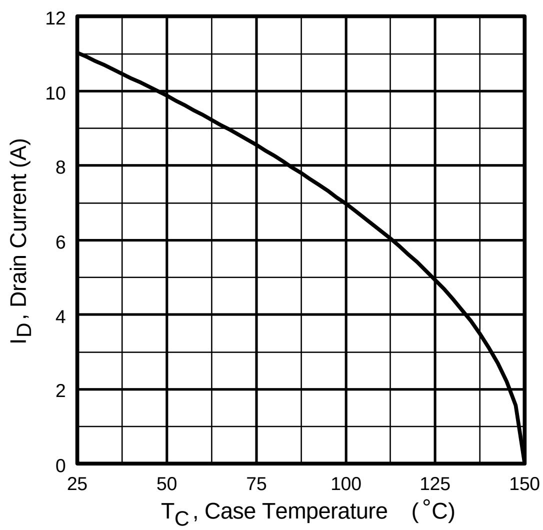


Fig 8. Maximum Safe Operating Area

Fig 6. On-Resistance Vs. Drain Current



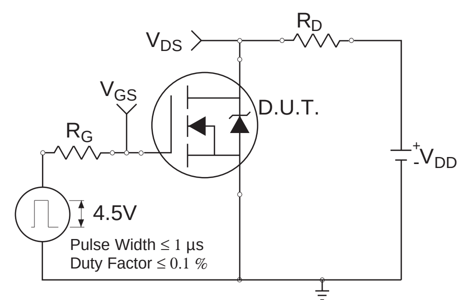


Fig 10a. Switching Time Test Circuit

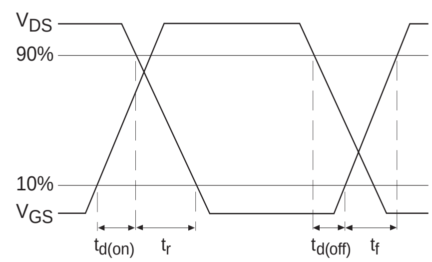


Fig 10b. Switching Time Waveforms

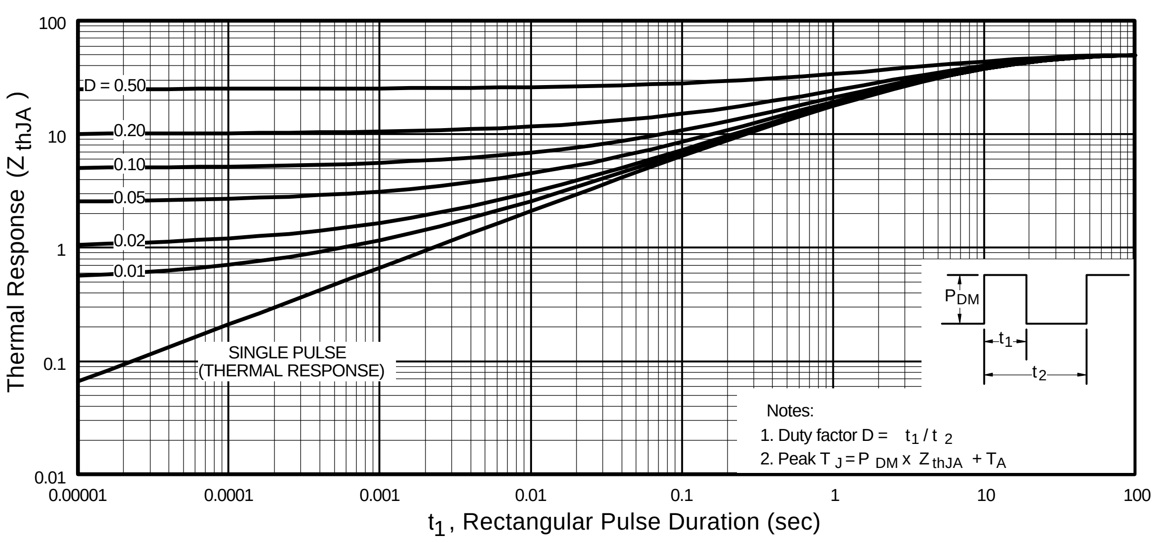


Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Case

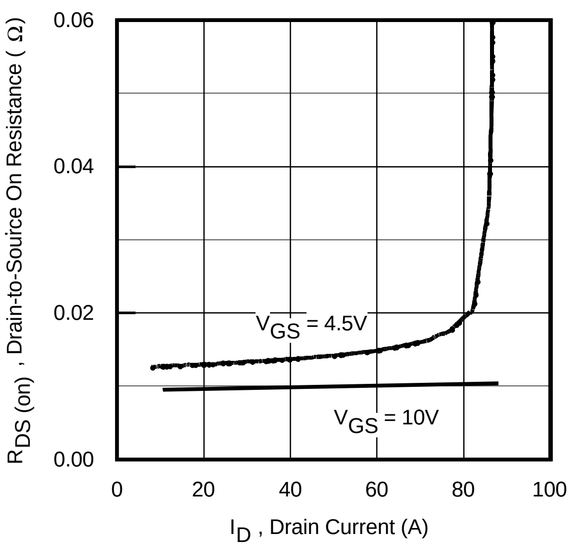


Fig 12. On-Resistance Vs. Drain Current

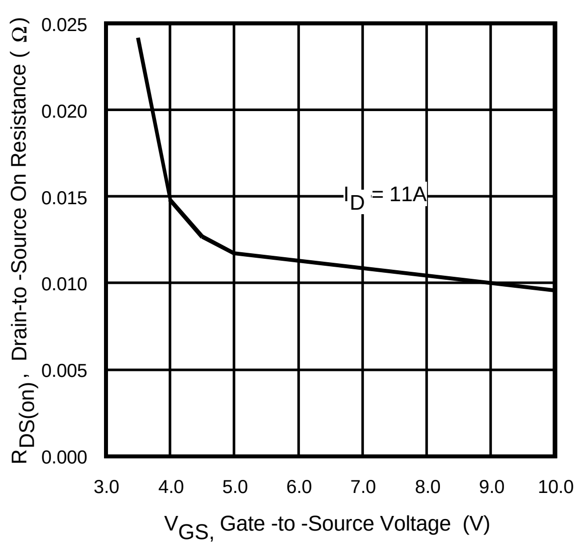


Fig 13. On-Resistance Vs. Gate Voltage

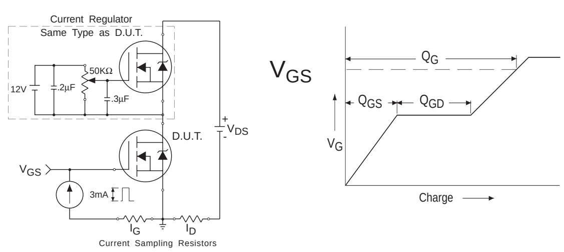
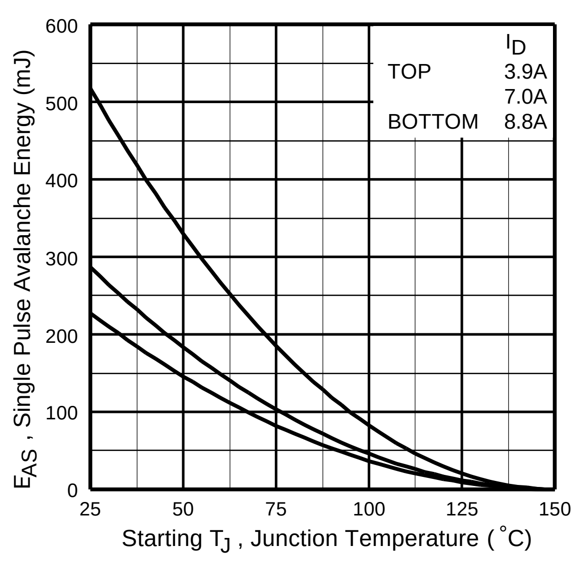


Fig 13a&b. Basic Gate Charge Test Circuit and Waveform



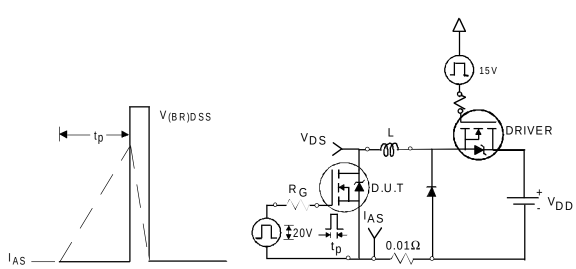
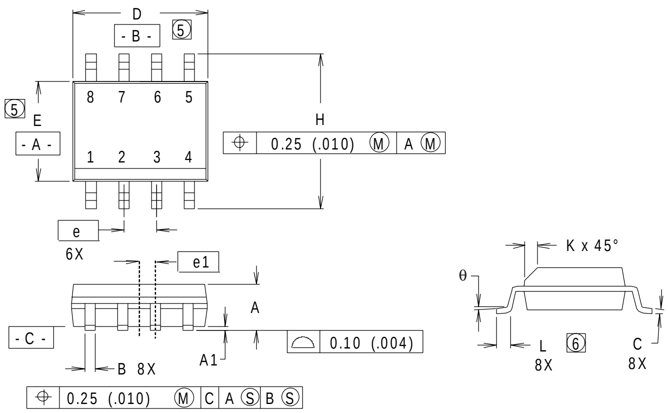


Fig 14a&b. Unclamped Inductive Test circuit and Waveforms

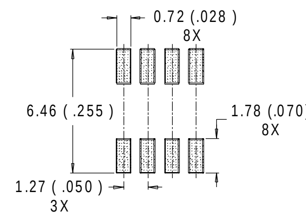
Fig 14c. Maximum Avalanche Energy Vs. Drain Current

SO-8 Package Details



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
B	.014	.018	0.36	0.46
C	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	0.16	.050	0.41	1.27
θ	0°	8°	0°	8°

RECOMMENDED FOOTPRINT

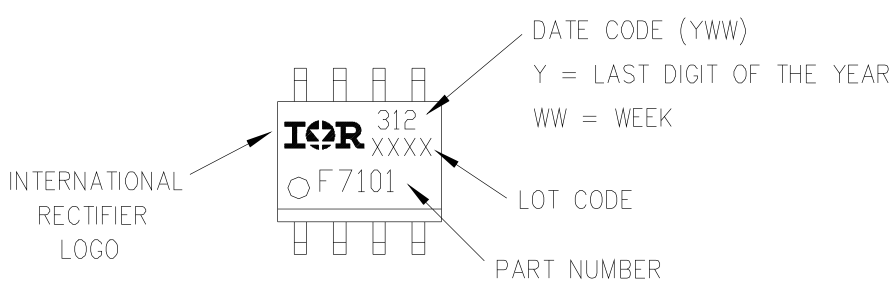


NOTES:

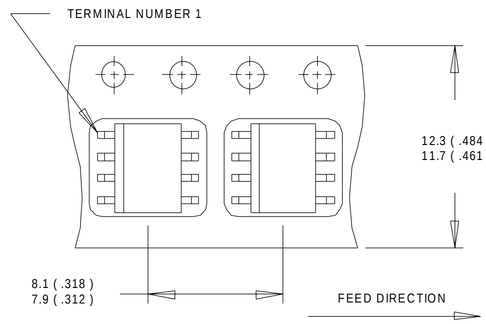
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.006).
6. DIMENSIONS IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

SO-8 Part Marking

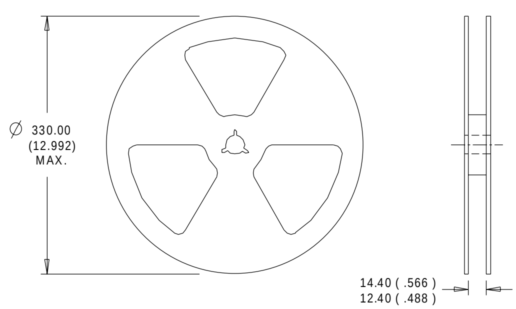
EXAMPLE: THIS IS AN IRF7101



SO-8 Tape and Reel



NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.

② Starting $T_J = 25°C$, L = 5.9mH $R_G = 25\Omega$, $I_{AS} = 8.8A$.

③ Pulse width ≤ 400µs; duty cycle ≤ 2%.

④ When mounted on 1 inch square copper board, t<10 sec

Data and specifications subject to change without notice.
This product has been designed and qualified for the Industrial market.
Qualification Standards can be found on IR's Web site.

International
IOR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
TAC Fax: (310) 252-7903
Visit us at www.irf.com for sales contact information.3/01